AMENDMENTS TO CLAIMS

1. (Currently Amended) A method comprising:

forming a chemically soluble coating on a plurality of exposed contacts on a surface of a circuit substrate and on the surface to a thickness greater than a distance of surface protrusion of a portion of the plurality of contacts; then

scribing through the substrate along scribe areas, wherein scribing comprises using a laser and generating debris on the coating; and

after scribing, removing ~~a portion of~~ the coating by a dissolution process to remove the debris, and to expose the plurality of contacts and the surface.

2. (Previously Presented) The method of claim 1, wherein each of a portion of the plurality of contacts comprise protruding bumps on the surface.

3. (Original) The method of claim 2, wherein the coating has a thickness of 5 to 35 microns.

4. (Currently Amended) The method of claim 2, further comprising sawing with a saw, completely through the substrate along the scribed areas prior to or simultaneous with removing the coating.

5. (Currently Amended) The method of claim 4, wherein sawing and removing ~~a portion of~~ the coating are done simultaneously.

6. (Canceled)

7. (Currently Amended) The method of claim 6, wherein removing ~~a portion of~~ the coating comprises removing the entire portion.

8. (Original) The method of claim 1, wherein a material of the chemically soluble coating is selected from the group consisting of methyl cellulose, polyvinyl alcohol, and resin flux.

9. (Currently Amended) A method comprising:

forming a circuit structure comprising a plurality of exposed contacts on a surface, a location of the exposed contacts defined by a plurality of scribe streets;

forming a coating comprising a chemically soluble material on the exposed contacts and on the surface to a thickness on the surface that is greater than a distance of surface protrusion of a portion of the plurality of contacts; then

scribing through the substrate along the scribe streets using a laser; and

after scribing, removing the coating from an area on the contacts and removing the coating thickness from the surface by a water dissolution process.

10. (Currently Amended) The method of claim 9, further comprising, after scribing, sawing with a saw completely through the substrate along the scribe streets prior to or simultaneous with removing the coating.

11. (Original) The method of claim 10, wherein sawing and removing the coating are done simultaneously.

12. (Original) The method of claim 10, wherein removing the coating comprises removing the entire coating.

13. (Original) The method of claim 10, wherein the material of the coating is selected from the group consisting of methyl cellulose, polyvinyl alcohol, and resin flux.

14. (Currently Amended) A method comprising:

coating a surface of a circuit substrate comprising a plurality of exposed contacts with a chemically soluble material; then

scribing the surface of the substrate along scribe areas, wherein scribing comprises using a laser and generating debris on the coating;

removing the coating to remove the debris, and to expose the plurality of contacts by removing all of the coating during a dissolution process; and

sawing completely the substrate in the scribe areas, wherein sawing is done using a saw, one of prior to and simultaneously with ~~and~~ removing the coating ~~are done simultaneously~~.

15. (Canceled)

16. (Canceled)

17. (New) The method of claim 1, wherein a material of the coating is an organic coating.

18. (New) The method of claim 4, wherein sawing comprises sawing with a saw, completely through the substrate along the scribed areas prior to removing the coating.